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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Takashi HIRAGA et al.

ATTN: PCT Branch

Application No.: 09/913,315

Docket No.: 110345

Filed: August 10, 2001

For: MODIFICATION METHOD OF SURFACE LAYER OF MOLDED RESIN ARTICLE, AND MODIFICATION APPARATUS OF SURFACE LAYER OF MOLDED RESIN ARTICLE

**NOTIFICATION OF ACCEPTANCE AND
FILING RECEIPT STATUS REQUEST**

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

The above-captioned patent application was filed on August 10, 2001. All 35 U.S.C 371 requirements were also satisfied on August 10, 2001. A copy of the postcard receipt is attached hereto.

The original Notification of Acceptance and Filing Receipt have not yet been received. It is respectfully requested that the original Notification of Acceptance and Filing Receipt be immediately forwarded to the attorneys of record at the address set forth below.

If there are any questions regarding this matter, please contact the undersigned at the telephone number set forth below.

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Respectfully submitted,

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The following papers have been filed: 533 Rec'd PCT/PTO 10 AUG 2001

PCT t, ck 121728 \$1514, PRELIM AM, ANXPER, REQ, 102pp spec/45clms/abs, 12pp drwngs
(1-12), DEC, assign t, ck 121729 \$40, ASSIGN, IDS pto 1449 srch rpt.
5refs/1abs/1conexp/2partrans

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Atty. File No.: 110345

Title (New Cases): MODIFICATION METHOD OF SURFACE LAYER OF MOLDED
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LAYER OF MOLDED RESIN ARTICLE

Sender's Initials: JAO/zmc

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